

PCN Number:	20200730000.1A		PCN Date:	Sep 10 2020							
Title:	Qualification of an alternate mount compound for Select Devices										
Customer Contact:	PCN Manager	Dept:	Quality Services								
Proposed 1st Ship Date:	Dec 8 2020		Estimated Sample Availability:	Date provided at sample request							
Change Type:											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site						
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials						
				<input type="checkbox"/>	Wafer Fab Process						
PCN Details											
Description of Change:											
<p>Revision A is to announce the <u>addition</u> of new devices on page 2 above that were not included on the original PCN notification.</p> <p>This PCN is to inform of an alternative mount compound qualification for the devices in the product affected section as follows:</p>											
		<table border="1"> <thead> <tr> <th style="width: 33%;">What</th> <th style="width: 33%;">Current</th> <th style="width: 33%;">Additional</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">Mount Compound</td> <td style="text-align: center;">SID#1400410101</td> <td style="text-align: center;">SID#47000011</td> </tr> </tbody> </table>		What	Current	Additional	Mount Compound	SID#1400410101	SID#47000011		
What	Current	Additional									
Mount Compound	SID#1400410101	SID#47000011									
Reason for Change:											
Continuity of supply											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Anticipated impact on Material Declaration											
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .								
Changes to product identification resulting from this PCN:											
None											
Product Affected:											
CSD17314Q2		CSD87503Q3E		CSD17314Q2T							
				CSD87503Q3ET							

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CSD87503Q3ET
PC	Preconditioning	Level 1 @ 260C	3/462/0
TC	**Temperature Cycle, -65C/150C	500 Cycles	3/231/0
UFAST	**Unbiased HAST, 130C	96 Hours	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/PASS
DS	Die Shear	QSS 009-009	3/30/0
WBP	Bond Pull	Wires	3/228/0
XRAY	X-ray	Devices	3/15/0
MSL	Moisture Sensitivity	Level 1 @ 260C	3/36/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours
- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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